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ELECTRICALLY CONDUCTIVE PASTE MATERIALS AND APPLICATIONS

ABSTRACT

A structure and method of fabrication are described. The structure is a combination of
5 a polymeric material (36) and particles (32), e.g. Cu, having an electrically conductive
coating (34), e.g. Sn. Heat is applied to fuse the coating of adjacent particles (32).

The polymeric material (36) is a thermoplastic. The structure is disposed between two
electrically conductive surfaces (40,42), e.g. chip and substrate pads, to provide
electrical interconnection and adhesion between their pads.

10 Fig. 4.